

	Type	L #	Hits	Search Text	DBs
1	BRS	L1	2	zheng near tieyu.in.	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
2	BRS	L2	2834	438/106.ccls.	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
3	BRS	L3	1297	2 and (solder)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
4	BRS	L4	399	2 and (solder near15 metal)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B

	Type	L #	Hits	Search Text	DBs
5	BRS	L5	20	2 and (solder near15 metal near15 base)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
6	BRS	L6	4	(solder) near15 (metal near cover) near15 (base near insulat\$3)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
7	BRS	L7	27	(solder) near15 (cover) near15 (base near insulat\$3)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
8	BRS	L8	1663	(solder) near15 (cover) near15 (substrate or base)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B

	Type	L #	Hits	Search Text	DBs
9	BRS	L9	11	((solder) near15 (cover) near15 (substrate or base)) near15 (current)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
10	BRS	L10	0	((solder) near15 (lid) near15 (substrate or base)) near15 (current)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
11	BRS	L11	154	((solder) near15 (lid or cover) near15 (substrate or base)) near15 (melt\$3)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
12	BRS	L12	3	((solder) near15 (lid or cover) near15 (substrate or base)) near15 (melt\$3) same (current)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B

	Type	L #	Hits	Search Text	DBs
13	BRS	L13	37	((solder) near15 (lid or cover) near15 (substrate or base)) same (current)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
14	BRS	L14	0	((solder) near15 (lid or cover) near15 (substrate or base)) same (current) near15 (pressure)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
15	BRS	L15	86	((solder) near15 (lid or cover) near15 (substrate or base)) same (pressure)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
16	BRS	L16	20	15 and current	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B

	Type	L #	Hits	Search Text	DBs
17	BRS	L17	9621	(remov\$3) near5 (pressure) near25 (cool\$3)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
18	BRS	L18	16	(remov\$3) near5 (pressure) near25 (cool\$3) near5 (solder)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
19	BRS	L19	14	(remov\$3) near5 (pressure) near5 (cool\$3) near5 (solder)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
20	BRS	L20	5	(remov\$3) near5 (pressure) near5 ((cool\$3) near5 (solder))	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B

	Type	L #	Hits	Search Text	DBs
21	BRS	L22	3	(packag\$3) near5 (pressure) near5 ((cool\$3) near5 (solder))	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
22	BRS	L21	90	(pressure) near5 ((cool\$3) near5 (solder))	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B

	U	1	Document ID	Title
1			US 20020043721 A1	Chip package with molded underfill
2			US 20010006759 A1	RADIATION SENSITIVE COMPOSITIONS
3			US 6560122 B2	Chip package with molded underfill

	U	1	Document ID	Title
4			US 6324069 B1	Chip package with molded underfill
5			US 5691395 A	Process of making flexible circuits and imaged coatings



	U	1	Document ID	Title
6			US 5366846 A	Photoimageable compositions comprising polybutadiene having internal epoxide groups
7			US 5331250 A	Thick film resistor for use in a vacuum and a high pressure discharge lamp having such a resistor
8			US 5262280 A	Radiation sensitive compositions
9			JP 61067940 A	SEALING METHOD FOR CERAMIC PACKAGE
10	X		US 6034470 A	Flat fluorescent lamp for background lighting or liquid crystal display - has strip-shaped anode and cathode electrodes and their associated current leads provided as conductor path structures
11	X		JP 62160744 A	Reinforcing connection of solder with substrate - by forming metal film on current conduction film and covering with solder to protect when etching conduction film NoAbstract Dwg 1/3